

## CPMT Officers

<b>President:</b>	William T. Chen	+1-408-986-6505
<b>VP (Technical):</b>	N.Rao Bonda	+1-480-413-6121
<b>VP (Conferences):</b>	Rolf Aschenbrenner	+49-30-46403-164
<b>VP (Publications):</b>	Paul B. Wesling	+1-408-331-0114
<b>VP (Education):</b>	Albert F. Puttlitz	+1-802-899-4692
<b>VP (Finance):</b>	Thomas G. Reynolds III	+1-850-897-7323
<b>Sr. Past Pres.:</b>	Rao Tummala	+1-404-894-9097
<b>Jr. Past Pres.:</b>	Phil Garrou	+1-919-248-9261
<b>Executive Director:</b>	Marsha Tickman	+1-732-562-5529

## Elected Board Members

**2009:**  
Philip C.H. Chan, Paul D. Franzon, R. Wayne Johnson, Kwang-Lung Lin, Petri Savolainen, and Leonard W. Schaper

**2008:**  
Vasudeva P. Atluri, Li Li, Dongkai Shangguan, Patrick Thompson, Klaus-Jürgen Wolter, and Kishio Yokouchi

**2007:**  
Eric O. Beyne, Steve J. Bezuk, Bahgat Sammakia, Rajen Chanchani, Kitty Pearsall, and C.P. Wong

## CPMT Society Newsletter

**Editor-in-Chief:** Vasudeva P. Atluri, email: [vpatluri@ieee.org](mailto:vpatluri@ieee.org)  
Tel: +1-480-554-0360, FAX: +1-480-563-0049

**Associate Editor:** Li Li, [li.li@ieee.org](mailto:li.li@ieee.org), +1-480-413-6653

**Associate Editor:** Debendra Mallik, [dmallik@ieee.org](mailto:dmallik@ieee.org), +1-480-554-5328

## CPMT Archival Publications

**Publications VP:**  
Paul Wesling, +1 408 331 0114; [p.wesling@ieee.org](mailto:p.wesling@ieee.org)

**Editor-in-Chief, CPMT Transactions:**  
Avram Bar-Cohen, Univ. of Maryland, +1-301-405-3173, [abc@eng.umd.edu](mailto:abc@eng.umd.edu)

**Transactions on Components & Pkg. Technologies, Editors in Chief:**  
Ricky S.W. Lee, Hong Kong Univ of Science & Technology, +852-2358-7203; [rickleey@ust.hk](mailto:rickleey@ust.hk)

Koneru Ramakrishna, Freescale, Inc., +1-512-933-2555; [rama@ieee.org](mailto:rama@ieee.org)

**Transactions on Advanced Packaging, Editor in Chief:**  
G. Subbarayan, Purdue University, Mechanical Engineering Dept., +1-765-494-9770; [ganeshs@purdue.edu](mailto:ganeshs@purdue.edu)

José E. Schutt-Ainé, University of Illinois at Urbana-Champaign, +1-217-244-7279, [jose@emlab.uiuc.edu](mailto:jose@emlab.uiuc.edu)

**Transactions on Electronics Pkg. Manufacturing, Editor in Chief:**  
R. Wayne Johnson, +1-334-844-1880, [johnson@eng.auburn.edu](mailto:johnson@eng.auburn.edu)

## Technical Committee Chairs

**TC-Assy - IC and Package Assembly:**  
Martin Goetz, IBM, +1-919-486-2409, [mgoetz@us.ibm.com](mailto:mgoetz@us.ibm.com)

**TC-ASTR - Environmental Stress & Reliability Test:**  
John E. Proulx, GM ATC, +1-310-257-3714, [john.proulx@gm.com](mailto:john.proulx@gm.com)

**TC-ECCC - Electrical Contacts, Connectors and Cables:**  
Jerry Witter, Chugai USA Inc., +1-847-244-6025, [g.witter@ieee.org](mailto:g.witter@ieee.org)

**TC-Ed - Education:**  
Rao R. Tummala, Georgia Tech., +1-404-894-9097, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**TC-EDMS - Electrical Design, Modeling and Simulation:**  
Madhavan Swaminathan, Georgia Tech, +1-404-894-3340, [madhavan.swaminathan@ee.gatech.edu](mailto:madhavan.swaminathan@ee.gatech.edu)

**TC-EM - Manufacturing - Design & Process:**  
Walter J. Trybula, SEMATECH, +1-512-356-3306, [w.trybula@ieee.org](mailto:w.trybula@ieee.org)

**TC-GEMP - Green Electronics Manufacturing and Packaging:**  
Nils F. Nissen, IZM, Berlin, +49-30-46403-139, [nils.nissen@izm.fraunhofer.de](mailto:nils.nissen@izm.fraunhofer.de)

**TC-HDSB - High Density PWB Packaging:**  
Yoshitaka Fukuoka, Weisti, +81-3-3475-0755, [weisti.fukuoka@rose.zero.ad.jp](mailto:weisti.fukuoka@rose.zero.ad.jp)

**TC-M - Materials:**  
Rajen Chanchani, Sandia Labs, +1-505-844-3482, [r.chanchani@ieee.org](mailto:r.chanchani@ieee.org)

**TC-MEMS - MEMS and Sensor Packaging:**  
Eric Jung, IZM, Berlin, +49-30-46403-161, email: [erju@izm.fhg.de](mailto:erju@izm.fhg.de)

**TC-NANO - Nano Packaging:**  
Rao Tummala, Georgia Tech., +1-404-894-9097, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**TC-OPTO - Fiber Optics & Photonics:**  
Susan Law, Australian Photonics/OFTC, +612-9351-1960, Email: [s.law@oftc.usyd.edu.au](mailto:s.law@oftc.usyd.edu.au)

**TC-PEP - Power Electronics Packaging:**  
Douglas Hopkins, SUNY Buffalo, +1-607-729-9949, [d.hopkins@ieee.org](mailto:d.hopkins@ieee.org)

**TC-RF+W - RF and Wireless:**  
Craig A. Gaw, Freescale, +1-480-413-5920, [c.a.gaw@ieee.org](mailto:c.a.gaw@ieee.org)

**TC-SP - Systems Packaging:**  
Cian O Mathuna, +353-21-4904350, [cian.omathuna@tyndall.ie](mailto:cian.omathuna@tyndall.ie)

**TC-Test - Electrical Test:**  
Bruce Kim, Univ of Alabama, +1-205-348-4972, [bruce.kim@ieee.org](mailto:bruce.kim@ieee.org)

**TC-Therm - Thermal Management & Thermomech. Design:**  
Tony Mak, Dallas Semiconductor, +1-972-371-4364, [t.mak@ieee.org](mailto:t.mak@ieee.org)

**TC-WLP - Wafer Level Packaging:**  
Michael Toepper, IZM, Berlin, +49-30-46403-603, [toepper@izm.fhg.de](mailto:toepper@izm.fhg.de)

## Strategic Program Directors

**Awards and Recognition:** Kitty Pearsall, [kittyp@us.ibm.com](mailto:kittyp@us.ibm.com)

**Conferences:** Rolf Aschenbrenner, [Rolf.Aschenbrenner@izm.fraunhofer.de](mailto:Rolf.Aschenbrenner@izm.fraunhofer.de)

**ECTC Integration:** C.P. Wong, [cp.wong@ieee.org](mailto:cp.wong@ieee.org)

**Educational Programs:** Albert F. Puttlitz, [a.f.puttlitz@ieee.org](mailto:a.f.puttlitz@ieee.org)

**Global Chapters and Membership:** Ralph W. Russell, II, [r.w.russell@ieee.org](mailto:r.w.russell@ieee.org)

**Publications:** Paul B. Wesling, [p.wesling@ieee.org](mailto:p.wesling@ieee.org)

**Student Programs:** William D. Brown, [wdb@enr.uark.edu](mailto:wdb@enr.uark.edu)

**Technical Programs:** Rao Bonda, [r.bonda@ieee.org](mailto:r.bonda@ieee.org)

**Region 8 Programs:** Johan Liu, [johan.liu@me.chalmers.se](mailto:johan.liu@me.chalmers.se)

**Region 10 Programs:** Charles Lee, [charles.lee@ieee.org](mailto:charles.lee@ieee.org)

## Standing Committee Chairs

**Awards:** Kitty Pearsall, [kittyp@us.ibm.com](mailto:kittyp@us.ibm.com)

**Chapter Development:** Ralph W. Russell, II, [r.w.russell@ieee.org](mailto:r.w.russell@ieee.org)

**Constitution and Bylaws:** Tony Mak, [t.mak@ieee.org](mailto:t.mak@ieee.org)

**Distinguished Lecturers:** Albert F. Puttlitz, [a.f.puttlitz@ieee.org](mailto:a.f.puttlitz@ieee.org)

**Educational Activities:** Vacant

**Fellows Evaluation:** Ching-Ping (C.P.) Wong, [cp.wong@ieee.org](mailto:cp.wong@ieee.org)

**Fellows Search:** David W. Palmer, [d.palmer@ieee.org](mailto:d.palmer@ieee.org)  
Rao Tummala, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**Finance:** Philip E. Garrou, [pgarrou@rti.com](mailto:pgarrou@rti.com)

**Long Range / Strategic Planning:** Rao Tummala, [rao.tummala@ee.gatech.edu](mailto:rao.tummala@ee.gatech.edu)

**Membership:** Ralph W. Russell, II, [r.w.russell@ieee.org](mailto:r.w.russell@ieee.org)

**Nominations:** Philip E. Garrou, [pgarrou@rti.com](mailto:pgarrou@rti.com)

## Distinguished Lecturers

**Program Director:** Albert F. Puttlitz

**Lecturers:** Avram Bar-Chen, H. Anthony Chan, Paul Franzon, George Harman, Badih El-Kareh, George Katopis, John H. Lau, Michael Lebby, Michael Pecht, Lue Martens, James E. Morris, T. Paul Parker, Karl Puttlitz, John M. Segelken, Ephraim Suhir, Paul Totta, Walter Trybula, Rao Tummala, Paul Wesling, C.P. Wong, and Ralph W. Wyndrum, Jr.

## Chapters and Student Branches

Refer to [www.cpmt.org](http://www.cpmt.org) for CPMT Society Chapters and Student Branches list

IEEE Components, Packaging, and Manufacturing Technology Society Newsletter is published quarterly by the Components, Packaging, and Manufacturing Technology Society of the Institute of Electrical and Electronics Engineers, Inc. Headquarters: 3 Park Avenue, 17th Floor, New York, NY 10016-5997. US \$1.00 per member per year is included in Society fee for each member of the Components, Packaging, and Manufacturing Technology Society. Printed in U.S.A. Periodicals postage paid at New York, NY, and at additional mailing offices. Postmaster: Send address changes to IEEE CPMT Newsletter, IEEE 445 Hoes Lane, Piscataway, NJ 08854. All rights reserved, copyright (c) 2005 by the CPMT Society of IEEE. Authors and Artists given full permission for further use of their contributions. For circulation information call IEEE Customer Service 800-701-4333, or FAX 908-981-9667.



**2007 Deadlines for Submitting Articles:**

**August 25<sup>th</sup>, 2007**

**November 25<sup>th</sup>, 2007**

**Members-only Web ([www.cpmt.org/mem/](http://www.cpmt.org/mem/))**

**UserName: [available to Members --**

**Password: join CPMT!]**